

Please amend the application as follows:

IN THE SPECIFICATION:

On page 10, lines 6-13, amend the Abstract as follows:

A semiconductor package substrate ~~(40)~~ (11) has an array of package sites ~~(13, 14, 16, 21, 22, and 23)~~ (13, 14, 16 and 21) that are substantially identical. The entire array of package sites ~~(13, 14, 16, 21, 22, and 23)~~ (13, 14, 16 and 21) is covered by an encapsulant (19). The individual package sites ~~(13, 14, 16, 21, 22, and 23)~~ (13, 14, 16 and 21) are singulated by sawing through the encapsulant (19) and the underlying semiconductor package substrate ~~(40)~~ (11).